

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product :May. 16, 2012

Expected First Date Code of Changed Product :1222

Last Date for Shipment of Unchanged Product :May. 16, 2012

Description of Change (From) :

Fairchild Semiconductor MDIP (16- and 20-lead) package currently assembled and tested at SiTEC Semiconductor Ltd (D.G.),China , Greatek Electronics Taiwan & Amkor Technology Philippines. Standardization of product marking with line 1 marked as FSC logo + plant code + date code + trace code and line 2 or 3 marked as device ID.

See below table for current site/package details.

BOM	SiTEC Semiconductor China	Greatek Electronics Taiwan	Amkor Technology Philippines
Device	SG6105ADZ & SG6105Z	FAN4800ANY, FAN4800ASNY, FAN4800ASNY_F116, FAN4800AUN, FAN4800CNY, FAN4800CSNY, FAN4801FNY_SN00170, FAN4801NY, FAN4801SNY, FAN4802LNY, FAN4802NY, FAN4802SNY, FAN6791NY, FAN6793NY, FAN4800IN_G & FAN4800CUN	ML4800CP and ML4824CP1
Wire	1.0 mil Au	1.0 mil Au	1.3 mil Au
Die Attach	Ablebond 84-1 LMISR4	Sumitomo CRM-1076DJ-G / Ablebond 84-3J	Ablebond 84-1 LMISR4
Leadframe	FU SHENG A194	FU SHENG A194	Hitachi C194
Mold Compound	Sumitomo EME-2100K(non green)	Sumitomo G600F	Sumitomo G600C
Plating	100% tin	100% tin	100% tin

Existing product with non standard marking:



Remark:

MF : Two digit device fab process indicator
X : First 6 digits of wafer lot ID
YWW : Yearcode and weekcode
Z : Assembly plant code

Description of Change (To) :

Qualification of additional MDIP package (16- and 20-lead) devices and green conversion for the 2 MDIP package in SiTEC Semiconductor Ltd (D.G.),China.

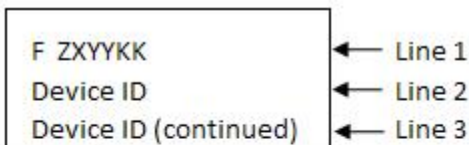
Refer to below table for future site/package details. No changes to current package specifications and dimension drawings.

BOM	SiTEC Semiconductor China		Greatek Electronics Taiwan
Device	SG6105ADZ,SG6105Z, FAN4801FNY_SN00170, FAN4800CNY, FAN4802LNY,FAN4802NY, FAN4800ASNY_F116, FAN4800ASNY, FAN4800ANY, FAN4800AUN, FAN4801NY, FAN4800CSNY, FAN4802SNY, FAN4801SNY, FAN6791NY,FAN6793NY & FAN4800CUN	FAN4800IN_G , ML4800CP & ML4824CP1	FAN4800ANY, FAN4800ASNY, FAN4800ASNY_F116, FAN4800AUN, FAN4800CNY, FAN4800CSNY, FAN4801FNY_SN00170, FAN4801NY, FAN4801SNY, FAN4802LNY, FAN4802NY, FAN4802SNY,FAN6791NY, FAN6793NY , FAN4800IN_G & FAN4800CUN
Wire	0.8 mil Au	1.0 mil Au	1.0 mil Au
Die Attach	Yiz-8511F / Henkel QM538MB	Yiz-8511F	Sumitomo CRM-1076DJ-G / Ablebond 84-3J
Leadframe	FU SHENG A194	FU SHENG A194	FU SHENG A194
Mold Compound	Edale ELER-8-560 (green)	Edale ELER-8-560 (green)	Sumitomo G600F (green)
Plating	100% tin	100% tin	100% tin

Remarks :

No change to Bill of material for green in Greatek's and Amkor's MDIP package.

Standardization of product marking format:



Remark:

F : Fairchild logo
Z : Plant code
X : one character year code
Y : two character week code
KK : Lot run code

Reason for Change:

SiTEC Semiconductor MDIP line is being added as an additional assembly and test site for increased manufacturing capacity for the affected products listed in this PCN in parallel with green conversion. The affected products will remain fully compliant to all published specifications and may be shipped interchangeably with existing products.

Affected Product(s):

FAN4800ANY	FAN4800ASNY	FAN4800ASNY_F116
FAN4800AUN	FAN4800CNY	FAN4800CSNY
FAN4800CUN	FAN4800IN_G	FAN4801FNY_SN00170
FAN4801NY	FAN4801SNY	FAN4802LNY
FAN4802NY	FAN4802SNY	FAN6791NY
FAN6793NY	ML4800CP	ML4824CP1
SG6105ADZ	SG6105Z	

Qualification Plan	Device	Package	Process	No. of Lots
QP2011017A	SG6105Z	DIP20	TSMC Process B	3

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Operating Life Test	125C, 5.5V	JESD22-A108	1000 hrs	0/231
Temperature Humidity Bias Test	85C,85%RH, 4.5V	JESD22-A101	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Autoclave	121C, 100%RH	JESD22-A110	96 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/231
Solderability	245C	JESD22-B102	5 sec	0/33
Resistance to Solder Heat	270C	JESD22-B106	10 sec	0/15

Qualification Plan	Device	Package	Process	No. of Lots
QP2011015A	SG6105ADY	DIP20	MXIC Process B	3

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Operating Life Test	125C, 5.5V	JESD22-A108	1000 hrs	0/231
Temperature Humidity Bias Test	85C,85%RH, 4.5V	JESD22-A101	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Autoclave	121C, 100%RH	JESD22-A110	96 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/231
Solderability	245C	JESD22-B102	5 sec	0/33
Resistance to Solder Heat	270C	JESD22-B106	10 sec	0/15

Qualification Plan	Device	Package	Process	No. of Lots
QP2011016A	FAN4800ASNY	DIP16	MXIC Process C	3

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Operating Life Test	125C, 26V	JESD22-A108	1000 hrs	0/231
Temperature Humidity Bias Test	85C,85%RH, 12V	JESD22-A101	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Autoclave	121C, 100%RH	JESD22-A110	96 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/231
Solderability	245C	JESD22-B102	5 sec	0/33
Resistance to Solder Heat	270C	JESD22-B106	10 sec	0/15